

JAMP AIS

List for application of the substance (Ver.1.03)

6/24/2014

[Summary]

- Directive RoHS (2011/65/EU) are summarized in the latest list of exemption applications.

"Symbol" is a directive for the same symbol.

"Body" of the content of the English text of the Directive is quoted, Chinese / Japanese was translated JAMP.

In addition, the exclusion list is sorted by application is granted the Federal Register. However, medical equipment, specialized applications that were excluded for monitoring and control equipment are listed at the bottom of the list. Exemptions 7(c)-IV (2012/50/EU) and 40 (2012/51/EU) are reviced.

Exemptions 1(g) (2014/14/EU) and exemptions (category 8-9) 12 and 21-34 (2014/1-13, 15, and 16/EU) are reviced.

- Directive ELV (2011/37/EC) are summarized in the latest list of exemption applications.

"Symbol" is a directive for the same symbol.

"Body" of the content of the English text of the Directive is quoted, Chinese / Japanese was translated JAMP. Exemptions 8(i) (2013/28/EU) is reviced.

- EACH Annex XVII (EU04) into a list of applications that can be used to limit, restrict use of the code displayed is selected from the popup list. This code is provided only limited by the list of substances of the substance corresponding to the REACH AnnexXVII. What you need to enter the appropriate code is the only substance group called DOT and DBT . "Body" of the contents of the quoted text is in English, Chinese / Japanese was translated JAMP.

- EU POPs (EU06) into a list of applications that can be used to limit, restrict use of the code displayed is selected from the popup list. This code is provided only limited by the list of substances of the substance corresponding to POPs. What you need to enter the appropriate code is the only substance group called PFOS . "Body" of the contents of the quoted text is in English, Chinese / Japanese was translated JAMP.

Symbol	English [RoHS]
No exemption	No exemption
Below threshold	Below threshold
1(a)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes < 30 W: not exceeding (per burner) 5 mg
1(a)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes < 30 W: not exceeding (per burner) 3.5 mg
1(a)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes < 30 W: not exceeding (per burner) 2.5 mg
1(b)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes ≥ 30 W and < 50 W: not exceeding (per burner) 5 mg
1(b)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes ≥ 30 W and < 50 W: not exceeding (per burner) 3.5 mg
1(c)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes ≥ 50 W and < 150 W: not exceeding (per burner) 5 mg
1(d)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes ≥ 150 W: not exceeding (per burner) 15 mg
1(e)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes with circular or square structural shape and tube diameter ≤ 17 mm
1(e)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes with circular or square structural shape and tube diameter ≤ 17 mm: not exceeding (per burner) 7 mg
1(f)	Mercury in single capped (compact) fluorescent lamps for special purposes: not exceeding (per burner) 5 mg
1(g)	Mercury in single capped (compact) fluorescent lamps for general lighting purposes < 30 W with a lifetime equal or above 20 000 h: not exceeding (per burner) 3.5 mg
2(a)(1)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (e.g. T2) for general lighting purposes not exceeding (per lamp): 5 mg
2(a)(1)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (e.g. T2) for general lighting purposes not exceeding (per lamp): 4 mg
2(a)(2)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter ≥ 9 mm and ≤ 17 mm (e.g. T5) for general lighting purposes not exceeding (per lamp): 5 mg
2(a)(2)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter ≥ 9 mm and ≤ 17 mm (e.g. T5) for general lighting purposes not exceeding (per lamp): 3 mg
2(a)(3)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and ≤ 28 mm (e.g. T8) for general lighting purposes not exceeding (per lamp): 5 mg
2(a)(3)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and ≤ 28 mm (e.g. T8) for general lighting purposes not exceeding (per lamp): 3.5 mg

2(a)(4)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (e.g. T12) for general lighting purposes not exceeding (per lamp): 5 mg
2(a)(4)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (e.g. T12) for general lighting purposes not exceeding (per lamp): 3.5 mg
2(a)(5)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with long lifetime ($\geq 25\,000$ h) for general lighting purposes not exceeding (per lamp): 8 mg
2(a)(5)	Mercury in double-capped linear fluorescent lamps Tri-band phosphor with long lifetime ($\geq 25\,000$ h) for general lighting purposes not exceeding (per lamp): 5 mg
2(b)(1)	Mercury in other fluorescent lamps Linear halophosphate lamps with tube > 28 mm (e.g. T10 and T12) not exceeding (per lamp):10 mg
2(b)(2)	Mercury in other fluorescent lamps Non-linear halophosphate lamps (all diameters) not exceeding (per lamp):15 mg
2(b)(3)	Mercury in other fluorescent lamps Non-linear tri-band phosphor lamps with tube diameter > 17 mm (e.g. T9)
2(b)(3)	Mercury in other fluorescent lamps Non-linear tri-band phosphor lamps with tube diameter > 17 mm (e.g. T9) not exceeding (per lamp): 15 mg
2(b)(4)	Mercury in other fluorescent lamps for other general lighting and special purposes (e.g. induction lamps)
2(b)(4)	Mercury in other fluorescent lamps for other general lighting and special purposes (e.g. induction lamps)not exceeding (per lamp): 15 mg
3(a)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes Short length (≤ 500 mm)
3(a)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes Short length (≤ 500 mm) not exceeding (per lamp): 3.5 mg
3(b)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes Medium length (> 500 mm and $\leq 1\,500$ mm)
3(b)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes Medium length (> 500 mm and $\leq 1\,500$ mm) not exceeding (per lamp):5 mg
3(c)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes Long length ($> 1\,500$ mm)
3(c)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes Long length ($> 1\,500$ mm) not exceeding (per lamp):13 mg
4(a)	Mercury in other low pressure discharge lamps (per lamp)
4(a)	Mercury in other low pressure discharge lamps not exceeding (per lamp):15 mg
4(b)-I	Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes with improved colour rendering index $R_a > 60$, $P \leq 155$ W

4(b)-I	Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes not exceeding (per burner) in lamps with improved colour rendering index $R_a > 60$, $P \leq 155$ W: 30 mg
4(b)-II	Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes with improved colour rendering index $R_a > 60$, 155 W $< P \leq 405$ W
4(b)-II	Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes with improved colour rendering index $R_a > 60$, 155 W $< P \leq 405$ W: 40 mg
4(b)-III	Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes with improved colour rendering index $R_a > 60$, $P > 405$ W
4(b)-III	Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes with improved colour rendering index $R_a > 60$, $P > 405$ W: 40 mg
4(c)-I	Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes $P \leq 155$ W
4(c)-I	Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes $P \leq 155$ W not exceeding (per burner):25 mg
4(c)-II	Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes 155 W $< P \leq 405$ W
4(c)-II	Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes 155 W $< P \leq 405$ W not exceeding (per burner):30 mg
4(c)-III	Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes $P > 405$ W
4(c)-III	Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes $P > 405$ W not exceeding (per burner):40 mg
4(d)	Mercury in High Pressure Mercury (vapour) lamps (HPMV). Expires on 13 April 2015
4(e)	Mercury in metal halide lamps (MH)
4(f)	Mercury in other discharge lamps for special purposes not specifically mentioned in this Annex
5(a)	Lead in glass of cathode ray tubes
5(b)	Lead in glass of fluorescent tubes not exceeding 0,2 % by weight
6(a)	Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight
6(b)	Lead as an alloying element in aluminium containing up to 0,4 % lead by weight
6(c)	Copper alloy containing up to 4 % lead by weight
7(a)	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7(b)	Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for telecommunications

7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
7(c)-II	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
7(c)-III	Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC.
7(c)-III	Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC may be used in spare parts for EEE placed on the market before 1 January 2013
7(c)-IV	Lead in PZT based dielectric ceramic materials for capacitors which are part of integrated circuits or discrete semiconductors
8(a)	Cadmium and its compounds in one shot pellet type thermal cut-offs.
8(a)	Cadmium and its compounds in one shot pellet type thermal cut-offs may be used in spare parts for EEE placed on the market before 1 January 2012
8(b)	Cadmium and its compounds in electrical contacts
9	Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0,75 % by weight in the cooling solution
9(b)	Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications
11(a)	Lead used in C-press compliant pin connector systems. May be used in spare parts for EEE placed on the market before 24 September 2010
11(b)	Lead used in other than C-press compliant pin connector systems.
11(b)	Lead used in other than C-press compliant pin connector systems may be used in spare parts for EEE placed on the market before 1 January 2013
12	Lead as a coating material for the thermal conduction module C-ring. May be used in spare parts for EEE placed on the market before 24 September 2010
13(a)	Lead in white glasses used for optical applications
13(b)	Cadmium and lead in filter glasses and glasses used for reflectance standards
14	Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.
14	Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight may be used in spare parts for EEE placed on the market before 1 January 2011
15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
16	Lead in linear incandescent lamps with silicate coated tubes. Expires on 1 September 2013

17	Lead halide as radiant agent in high intensity discharge (HID) lamps used for professional reprography applications
18(a)	Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as speciality lamps for diazoprinting reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba) $2\text{MgSi}_2\text{O}_7$:Pb)
18(b)	Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi_2O_5 :Pb)
19	Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact energy saving lamps (ESL). Expires on 1 June 2011
20	Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs). Expires on 1 June 2011
21	Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses
23	Lead in finishes of fine pitch components other than connectors with a pitch of 0,65 mm and less. May be used in spare parts for EEE placed on the market before 24 September 2010
24	Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors
25	Lead oxide in surface conduction electron emitter displays (SED) used in structural elements, notably in the seal frit and frit ring
26	Lead oxide in the glass envelope of black light blue lamps. Expires on 1 June 2011
29	Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC (1)
30	Cadmium alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers with sound pressure levels of 100 dB (A) and more
31	Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting)
32	Lead oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes
33	Lead in solders for the soldering of thin copper wires of 100 μm diameter and less in power transformers
34	Lead in cermet-based trimmer potentiometer elements
37	Lead in the plating layer of high voltage diodes on the basis of a zinc borate glass body
38	Cadmium and cadmium oxide in thick film pastes used on aluminium bonded beryllium oxide
39	Cadmium in colour converting II-VI LEDs (< 10 μg Cd per mm^2 of light-emitting area) for use in solid state illumination or display systems. Expires on 1 July 2014
40	Cadmium in photoresistors for analogue optocouplers applied in professional audio equipment

1	Lead, cadmium and mercury in detectors for ionising radiation
2	Lead bearings in X-ray tubes
3	Lead in electromagnetic radiation amplification devices: micro-channel plate and capillary plate
4	Lead in glass frit of X-ray tubes and image intensifiers and lead in glass frit binder for assembly of gas lasers and for vacuum tubes that convert electromagnetic radiation into electrons
5	Lead in shielding for ionising radiation
6	Lead in X-ray test objects
7	Lead stearate X-ray diffraction crystals
8	Radioactive cadmium isotope source for portable X-ray fluorescence spectrometers
1a	Lead and cadmium in ion selective electrodes including glass of pH electrodes
1b	Lead anodes in electrochemical oxygen sensors
1c	Lead, cadmium and mercury in infra-red light detectors
1d	Mercury in reference electrodes: low chloride mercury chloride, mercury sulphate and mercury oxide
9	Cadmium in helium-cadmium lasers
10	Lead and cadmium in atomic adsorption spectroscopy lamps
11	Lead in alloys as a superconductor and thermal conductor in MRI
12	Lead and cadmium in metallic bonds to superconducting materials in MRI and SQUID detectors
12	Lead and cadmium in metallic bonds creating superconducting magnetic circuits in MRI, SQUID, NMR (Nuclear Magnetic Resonance) or FTMS (Fourier Transform Mass Spectrometer) detectors.
13	Lead in counterweights
14	Lead in single crystal piezoelectric materials for ultrasonic transducers
15	Lead in solders for bonding to ultrasonic transducers
16	Mercury in very high accuracy capacitance and loss measurement bridges and in high frequency RF switches and relays in monitoring and control instruments not exceeding 20 mg of mercury per switch or relay

17	Lead in solders in portable emergency defibrillators
18	Lead in solders of high performance infrared imaging modules to detect in the range 8–14 μm
19	Lead in Liquid crystal on silicon (LCoS) displays
20	Cadmium in X-ray measurement filters
21	Cadmium in phosphor coatings in image intensifiers for X-ray images.
21	Cadmium in phosphor coatings in spare parts for X-ray systems placed on the EU market before 1 January 2020.
22	Lead acetate marker for use in stereotactic head frames for use with CT and MRI and in positioning systems for gamma beam and particle therapy
23	Lead as an alloying element for bearings and wear surfaces in medical equipment exposed to ionising radiation.
24	Lead enabling vacuum tight connections between aluminium and steel in X-ray image intensifiers.
25	Lead in the surface coatings of pin connector systems requiring nonmagnetic connectors which are used durably at a temperature below – 20 °C under normal operating and storage conditions.
26	Lead in: solders on printed circuit boards; termination coatings of electrical and electronic components and coatings of printed circuit boards; solders for connecting wires and cables; and solders connecting transducers and sensors; that are used durably at a temperature below – 20 °C under normal operating and storage conditions.
27	Lead in: solders; termination coatings of electrical and electronic components and printed circuit boards; and connections of electrical wires, shields and enclosed connectors; which are used in (a) magnetic fields within the sphere of 1 m radius around the isocentre of the magnet in medical magnetic resonance imaging equipment, including patient monitors designed to be used within this sphere, or (b) magnetic fields within 1 m distance from the external surfaces of cyclotron magnets, magnets for beam transport and beam direction control applied for particle therapy.
28	Lead in solders for mounting cadmium telluride and cadmium zinc telluride digital array detectors to printed circuit boards.
29	Lead in alloys, as a superconductor or thermal conductor, used in cryo-cooler cold heads and/or in cryo-cooled cold probes and/or in cryo-cooled equipotential bonding systems, in medical devices (category 8) and/or in industrial monitoring and control instruments.
30	Hexavalent chromium in alkali dispensers used to create photocathodes in X-ray image intensifiers.
30	Hexavalent chromium in alkali dispensers used to create photocathodes in spare parts for X-ray systems placed on the EU market before 1 January 2020.

31	Lead, cadmium and hexavalent chromium in reused spare parts, recovered from medical devices placed on the market before 22 July 2014 and used in category 8 equipment placed on the market before 22 July 2021, provided that reuse takes place in auditable closed-loop business-to-business return systems, and that the reuse of parts is notified to the consumer.
32	Lead in solders on printed circuit boards of detectors and data acquisition units for Positron Emission Tomographs which are integrated into Magnetic Resonance Imaging equipment.
33	Lead in solders on populated printed circuit boards used in Directive 93/42/EEC class IIa mobile medical devices other than portable emergency defibrillators.
33	Lead in solders on populated printed circuit boards used in Directive 93/42/EEC class IIb mobile medical devices other than portable emergency defibrillators.
34	Lead as an activator in the fluorescent powder of discharge lamps when used for extracorporeal photopheresis lamps containing BSP (BaSi_2O_5 :Pb) phosphors.

Symbol	English [ELV]
No exemption	No exemption
Below threshold	Below threshold
1(a)	Steel for machining purposes and batch hot dip galvanised steel components containing up to 0,35 % lead by weight
1(b)	Continuously galvanised steel sheet containing up to 0,35 % lead by weight. Vehicles type approved before 1 January 2016 and spare parts for these vehicles
2(a)	Aluminium for machining purposes with a lead content up to 2 % by weight As spare parts for vehicles put on the market before 1 July 2005
2(b)	Aluminium with a lead content up to 1,5 % by weight As spare parts for vehicles put on the market before 1 July 2008
2(c)	Aluminium with a lead content up to 0,4 % by weight
3	Copper alloy containing up to 4 % lead by weight
4(a)	Bearing shells and bushes As spare parts for vehicles put on the market before 1 July 2008
4(b)	Bearing shells and bushes in engines, transmissions and air conditioning compressors 1 July 2011 and spare parts for vehicles put on the market before 1 July 2011
5	Batteries
6	Vibration dampers Vehicles type approved before 1 January 2016 and spare parts for these vehicles
7(a)	Vulcanising agents and stabilisers for elastomers in brake hoses, fuel hoses, air ventilation hoses, elastomer/metal parts in the chassis applications, and engine mountings As spare parts for vehicles put on the market before 1 July 2005
7(b)	Vulcanising agents and stabilisers for elastomers in brake hoses, fuel hoses, air ventilation hoses, elastomer/metal parts in the chassis applications, and engine mountings containing up to 0,5 % lead by weight As spare parts for vehicles put on the market before 1 July 2006
7(c)	Bonding agents for elastomers in powertrain applications containing up to 0,5 % lead by weight As spare parts for vehicles put on the market before 1 July 2009
8(a)	Lead in solders to attach electrical and electronic components to electronic circuit boards and lead in finishes on terminations of components other than electrolyte aluminium capacitors, on component pins and on electronic circuit boards Vehicles type approved before 1 January 2016 and spare parts for these vehicles
8(b)	Lead in solders in electrical applications other than soldering on electronic circuit boards or on glass Vehicles type approved before 1 January 2011 and spare parts for these vehicles
8(c)	Lead in finishes on terminals of electrolyte aluminium capacitors Vehicles type approved before 1 January 2013 and spare parts for these vehicles
8(d)	Lead used in soldering on glass in mass airflow sensors Vehicles type approved before 1 January 2015 and spare parts of such vehicles
8(e)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

8(f)	Lead in compliant pin connector systems
8(g)	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
8(h)	Lead in solder to attach heat spreaders to the heat sink in power semiconductor assemblies with a chip size of at least 1 cm ² of projection area and a nominal current density of at least 1 A/mm ² of silicon chip area
8(i)	Lead in solders in electrical glazing applications on glass except for soldering in laminated glazing Vehicles type approved before 1 January 2016 and after that date as spare parts for these vehicles.
8(j)	Lead in solders for soldering in laminated glazing
9	Valve seats As spare parts for engine types developed before 1 July 2003
10(a)	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound. This exemption does not cover the use of lead in glass in bulbs and glaze of spark plugs, dielectric ceramic materials of components listed under 10(b), 10(c) and 10(d). X [5] (for components other than piezo in engines)
10(b)	Lead in PZT based dielectric ceramic materials of capacitors being part of integrated circuits or discrete semiconductors
10(c)	Lead in dielectric ceramic materials of capacitors with a rated voltage of less than 125 V AC or 250 V DC Vehicles type approved before 1 January 2016 and spare parts for these vehicles
10(d)	Lead in the dielectric ceramic materials of capacitors compensating the temperature-related deviations of sensors in ultrasonic sonar systems
11	Pyrotechnic initiators Vehicles type approved before 1 July 2006 and spare parts for these vehicles
12	Lead-containing thermoelectric materials in automotive electrical applications to reduce CO ₂ emissions by recuperation of exhaust heat Vehicles type approved before 1 January 2019 and spare parts for these vehicles
13(a)	Corrosion preventive coatings As spare parts for vehicles put on the market before 1 July 2007
13(b)	Corrosion preventive coatings related to bolt and nut assemblies for chassis applications As spare parts for vehicles put on the market before 1 July 2008
14	As an anti-corrosion agent of the carbon steel cooling system in absorption refrigerators in motorcaravans up to 0,75 weight -% in the cooling solution except where the use of other cooling technologies is practicable (i.e. available on the market for the application in motor caravans) and does not lead to negative environmental, health and/or consumer safety impacts
15(a)	Discharge lamps for headlight application Vehicles type approved before 1 July 2012 and spare parts for these vehicles
15(b)	Fluorescent tubes used in instrument panel displays Vehicles type approved before 1 July 2012 and spare parts for these vehicles
16	Batteries for electrical vehicles As spare parts for vehicles put on the market before 31 December 2008

Symbol	English [REACH Annex XVII]
DBT-0	No information to specify the intended use
DBT-1	Any one-component and two-component room temperature vulcanization sealants (RTV-1 and RTV-2 sealant) and adhesives which apply to the general public but are not intended for food contact
DBT-2	Any paints and coating containing DBT compounds as catalysts when applied on articles which apply to the general public but are not intended for food contact
DBT-3	Any soft polyvinyl chloride (PVC) profiles whether by themselves or co extruded with hard PVC which apply to the general public but are not intended for food contact
DBT-4	Any fabrics coated with PVC containing DBT compounds as stabilizers when intended for outdoor applications which apply to the general public but are not intended for food contact
DBT-5	Any outdoor rainwater pipes, gutters and fittings, as well as covering materials for roofing and facades which apply to the general public but are not intended for food contact
DBT-98	Any use which the content is not greater than the threshold, the equivalent of 0.1% by weight of tin
DBT-99	Not applicable
DOT-0	No information to specify the intended use
DOT-1	Any articles other than the following articles <ul style="list-style-type: none"> - textile articles intended to come into contact with the skin, - gloves, - footwear or part of footwear intended to come into contact with the skin, - walls and floor coverings, - childcare articles, - female hygiene products, - nappies, - two-component room temperature vulcanization molding kits (RTV-2 molding kits)
DOT-98	Any use which the content is not greater than the threshold, the equivalent of 0.1% by weight of tin
DOT-99	Not applicable

Symbol	English [POPs]
PFOS-0	No information to specify the intended use
PFOS-1	Any photoresists or anti-reflective coatings for photolithography processes
PFOS-2	Any photographic coatings applied to films, papers, or printing plates
PFOS-3	Any mist suppressants for non-decorative hard chromium (VI) plating
PFOS-4	Wetting agents for use in controlled electroplating systems
PFOS-5	Any hydraulic fluids for aviation
PFOS-98	Any mixtures in concentrations less than 10 mg/kg (0.001% by weight), or where the concentration of PFOS is less than 0.1% by weight calculated with reference to the mass of structurally or microstructurally distinct parts that contain PFOS, any textiles or other coated materials, or where the amount of PFOS is less than 1µg/m ² of the coated material
PFOS-99	Not applicable